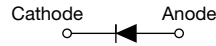
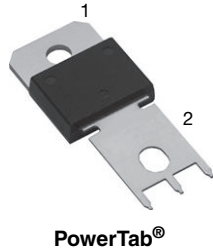


# Ultrafast Soft Recovery Diode, 150 A FRED Pt®



## FEATURES

- Ultrafast recovery time
- 175 °C max. operating junction temperature
- Screw mounting only
- Designed and qualified according to JEDEC®-JESD 47
- PowerTab® package
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
COMPLIANT

## BENEFITS

- Reduced RFI and EMI
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

## DESCRIPTION / APPLICATIONS

These diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for HF welding, power converters and other applications where switching losses are not significant portion of the total losses.

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	150 A
$V_R$	200 V
$V_F$ at $I_F$	0.79 V
$t_{rr}$ (typ.)	See recovery table
$T_J$ max.	175 °C
Package	PowerTab®
Circuit configuration	Single

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Cathode to anode voltage	$V_R$		200	V
Continuous forward current	$I_{F(AV)}$	$T_C = 116\text{ °C}$	150	A
Single pulse forward current	$I_{FSM}$	$T_C = 25\text{ °C}$	1600	
Maximum repetitive forward current	$I_{FRM}$	Square wave, 20 kHz	380	
Operating junction and storage temperatures	$T_J, T_{Stg}$		-55 to +175	°C

ELECTRICAL SPECIFICATIONS ( $T_J = 25\text{ °C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	$V_{BR}, V_R$	$I_R = 100\text{ }\mu\text{A}$	200	-	-	V
Forward voltage	$V_F$	$I_F = 150\text{ A}$	-	0.99	1.13	
		$I_F = 150\text{ A}, T_J = 175\text{ °C}$	-	0.79	0.90	
Reverse leakage current	$I_R$	$V_R = V_R$ rated	-	-	50	$\mu\text{A}$
		$T_J = 150\text{ °C}, V_R = V_R$ rated	-	-	2	mA
Junction capacitance	$C_T$	$V_R = 200\text{ V}$	-	180	-	pF
Series inductance	$L_S$	Measured lead to lead 5 mm from package body	-	3.5	-	nH



DYNAMIC RECOVERY CHARACTERISTICS (T <sub>J</sub> = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = 1.0 A, di <sub>F</sub> /dt = 200 A/μs, V <sub>R</sub> = 30 V	-	-	45	ns
		T <sub>J</sub> = 25 °C	-	34	-	
		T <sub>J</sub> = 125 °C	-	58	-	
Peak recovery current	I <sub>RRM</sub>	T <sub>J</sub> = 25 °C	-	4.5	-	A
		T <sub>J</sub> = 125 °C	-	9.0	-	
Reverse recovery charge	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C	-	87	-	nC
		T <sub>J</sub> = 125 °C	-	300	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Thermal resistance, junction to case	R <sub>thJC</sub>		-	-	0.35	K/W
Thermal resistance, case to heatsink	R <sub>thCS</sub>	Mounting surface, flat, smooth, and greased	-	0.2	-	
Weight			-	-	5.02	g
			-	0.18	-	oz.
Mounting torque			1.2 (10)	-	2.4 (20)	N · m (lb · in)
Marking device		Case style PowerTab®				150EBU02

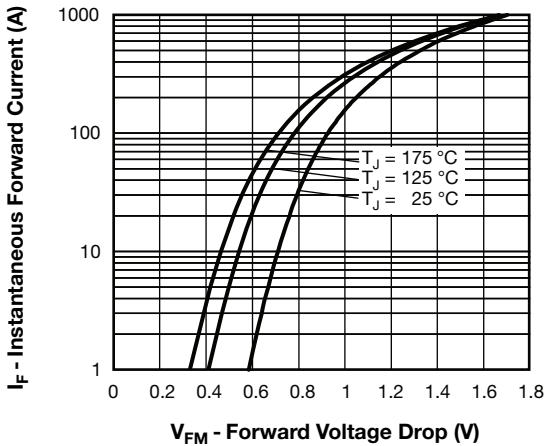


Fig. 1 - Maximum Forward Voltage Drop Characteristics

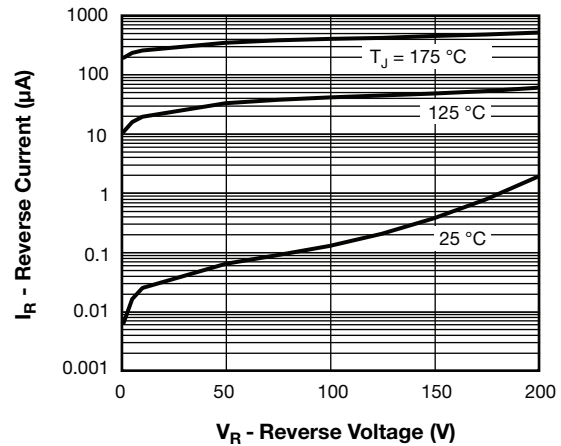


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

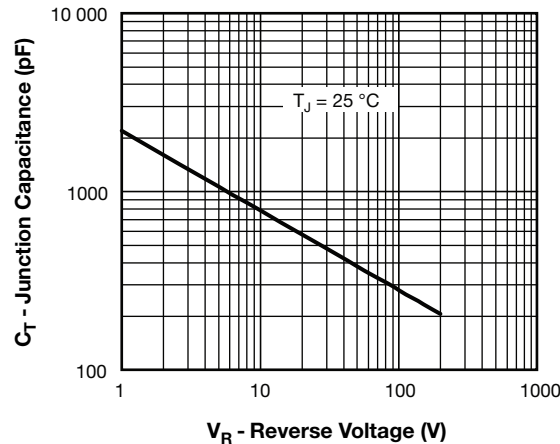


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

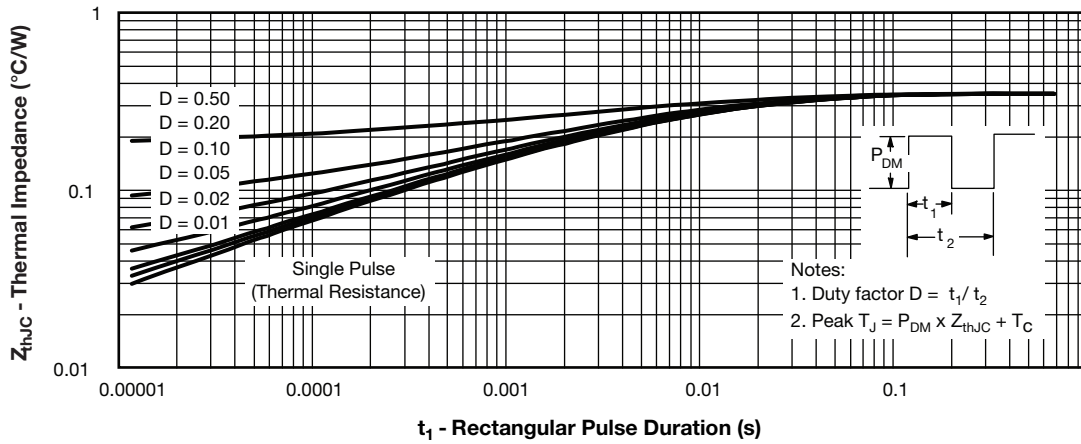


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics

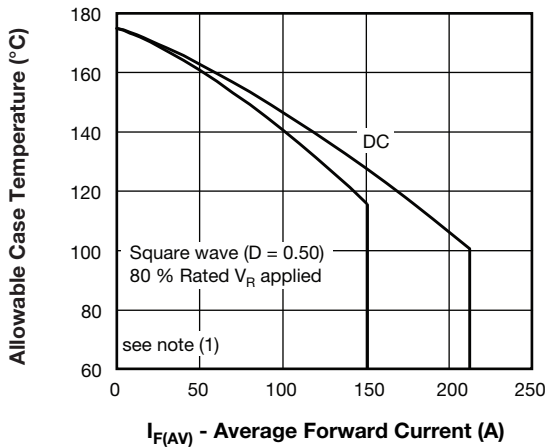


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

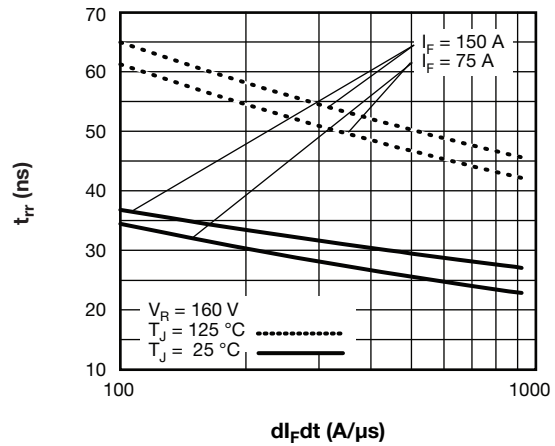


Fig. 7 - Typical Reverse Recovery Time vs.  $dI_F/dt$

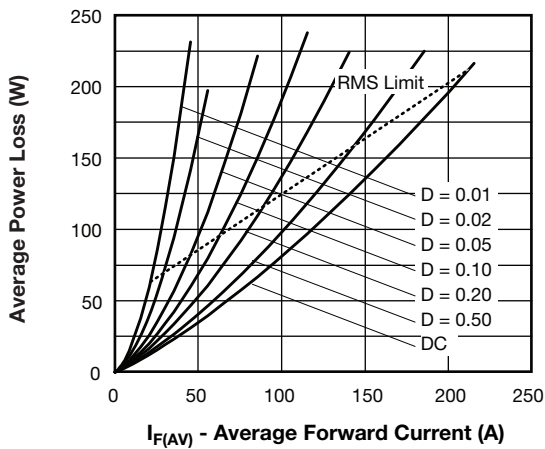


Fig. 6 - Forward Power Loss Characteristics

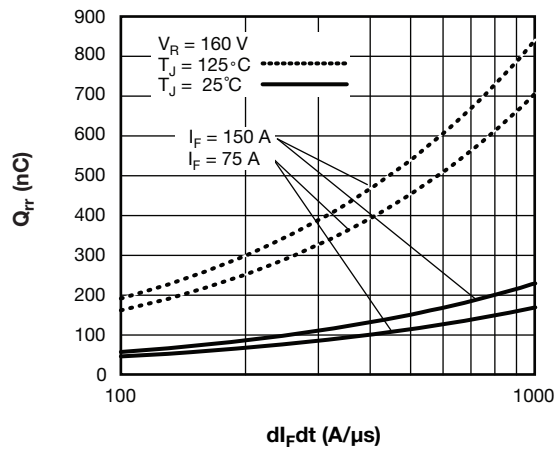


Fig. 8 - Typical Stored Charge vs.  $dI_F/dt$

**Note**

- (1) Formula used:  $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$ ;
- $P_d$  = forward power loss =  $I_{F(AV)} \times V_{FM}$  at  $(I_{F(AV)}/D)$  (see fig. 6);
- $P_{dREV}$  = inverse power loss =  $V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1} = 80\%$  rated  $V_R$

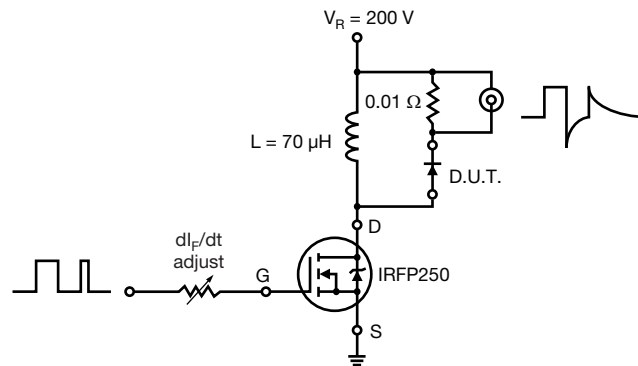
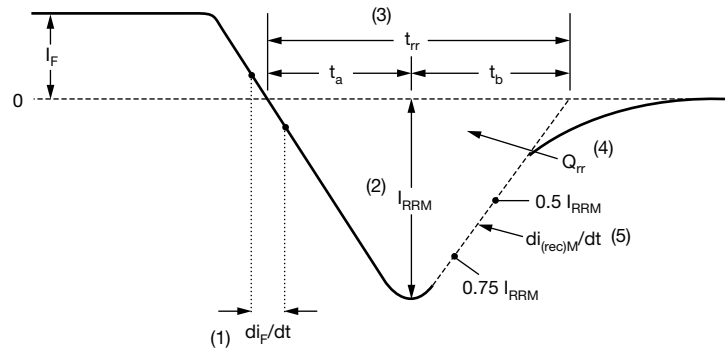


Fig. 9 - Reverse Recovery Parameter Test Circuit



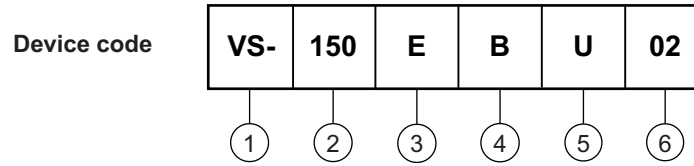
- (1)  $di_F/dt$  - rate of change of current through zero crossing
- (2)  $I_{RRM}$  - peak reverse recovery current
- (3)  $t_{rr}$  - reverse recovery time measured from zero crossing point of negative going  $I_F$  to point where a line passing through  $0.75 I_{RRM}$  and  $0.50 I_{RRM}$  extrapolated to zero current.
- (4)  $Q_{rr}$  - area under curve defined by  $t_{rr}$  and  $I_{RRM}$
- (5)  $di_{(rec)M}/dt$  - peak rate of change of current during  $t_b$  portion of  $t_{rr}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

Fig. 10 - Reverse Recovery Waveform and Definitions



**ORDERING INFORMATION TABLE**



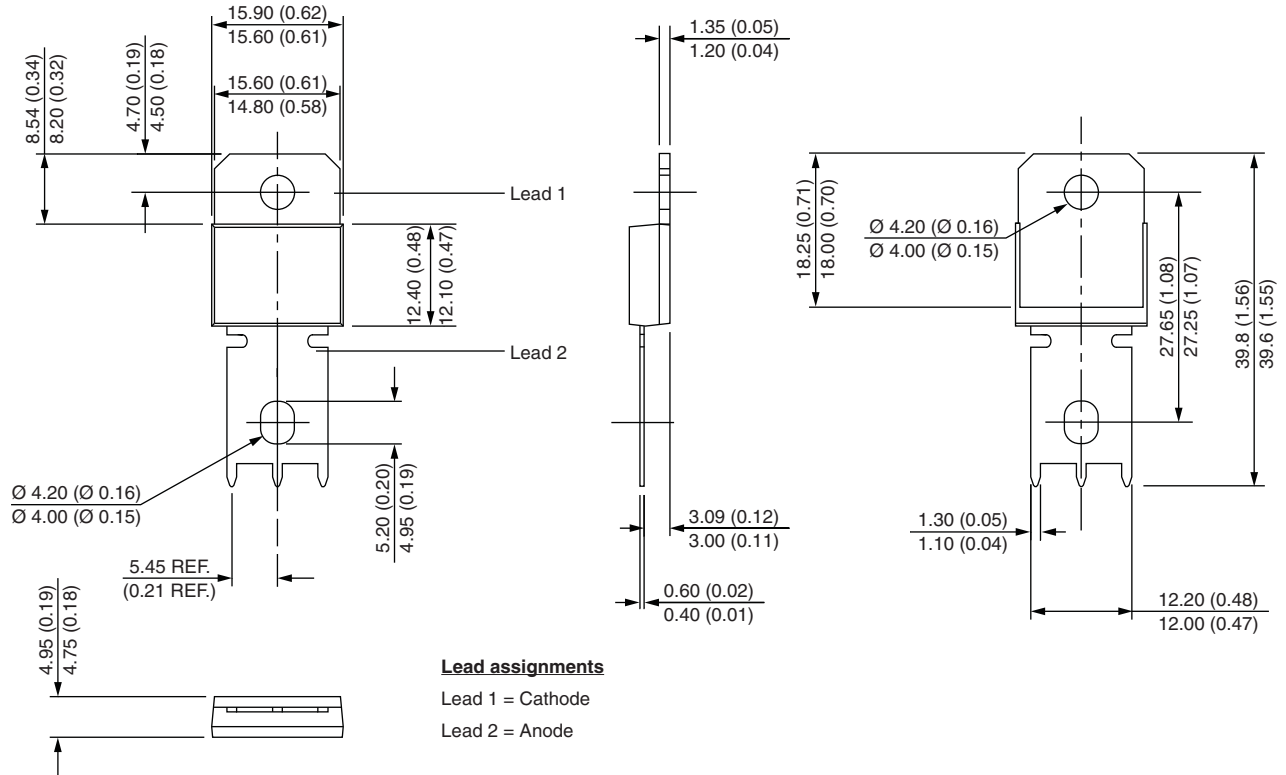
- 1** - Vishay Semiconductors product
- 2** - Current rating (150 = 150 A)
- 3** - Single diode
- 4** - PowerTab® (ultrafast/hyperfast only)
- 5** - Ultrafast recovery
- 6** - Voltage rating (02 = 200 V)

LINKS TO RELATED DOCUMENTS	
Dimensions	<a href="http://www.vishay.com/doc?95240">www.vishay.com/doc?95240</a>
Part marking information	<a href="http://www.vishay.com/doc?95370">www.vishay.com/doc?95370</a>
Application note	<a href="http://www.vishay.com/doc?95179">www.vishay.com/doc?95179</a>
SPIICE model	<a href="http://www.vishay.com/doc?96503">www.vishay.com/doc?96503</a>



## PowerTab®

**DIMENSIONS** in millimeters (inches)





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